

Dual 1:2 Low Additive Jitter LVDS Buffer

Check for Samples: [CDCLVD2102](#)

FEATURES

- Dual 1:2 Differential Buffer
- Low Additive Jitter <300 fs RMS in 10-kHz to 20-MHz
- Low Within Bank Output Skew of 15 ps (Max)
- Universal Inputs Accept LVDS, LVPECL, LVCMOS
- One Input Dedicated for Two Outputs
- Total of 4 LVDS Outputs, ANSI EIA/TIA-644A Standard Compatible
- Clock Frequency up to 800 MHz
- 2.375–2.625V Device Power Supply
- LVDS Reference Voltage, V_{AC_REF} , Available for Capacitive Coupled Inputs
- Industrial Temperature Range –40°C to 85°C
- Packaged in 3mm × 3mm 16-Pin QFN (RGT)
- ESD Protection Exceeds 3 kV HBM, 1 kV CDM

APPLICATIONS

- Telecommunications/Networking
- Medical Imaging
- Test and Measurement Equipment
- Wireless Communications
- General Purpose Clocking

DESCRIPTION

The CDCLVD2102 clock buffer distributes two clock inputs (IN0, IN1) to a total of 4 pairs of differential LVDS clock outputs (OUT0, OUT3). Each buffer block consists of one input and 2 LVDS outputs. The inputs can either be LVDS, LVPECL, or LVCMOS.

The CDCLVD2102 is specifically designed for driving 50-Ω transmission lines. If driving the inputs in single ended mode, the appropriate bias voltage (V_{AC_REF}) should be applied to the unused negative input pin.

Using the control pin (EN), outputs can be either disabled or enabled. If the EN pin is left open two buffers with all outputs are enabled, if switched to a logical "0" both buffers with all outputs are disabled (static logical "0"), if switched to a logical "1", one buffer with two outputs is disabled and another buffer with two outputs is enabled. The part supports a fail safe function. It incorporates an input hysteresis, which prevents random oscillation of the outputs in absence of an input signal.

The device operates in 2.5V supply environment and is characterized from –40°C to 85°C (ambient temperature). The CDCLVD2102 is packaged in small 16-pin, 3-mm × 3-mm QFN package.

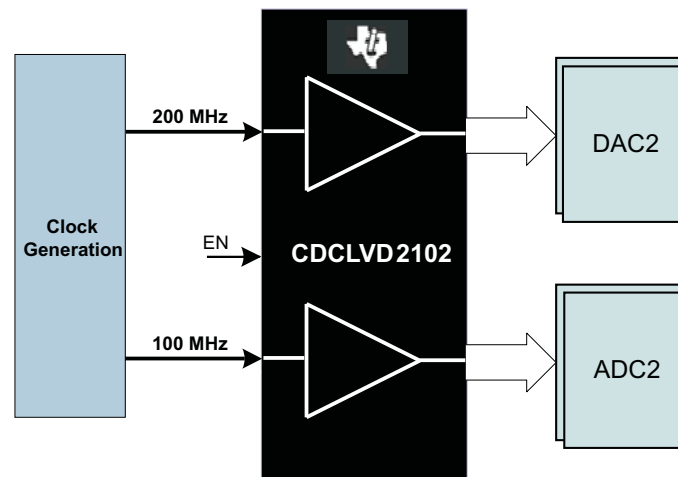


Figure 1. Application Example



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

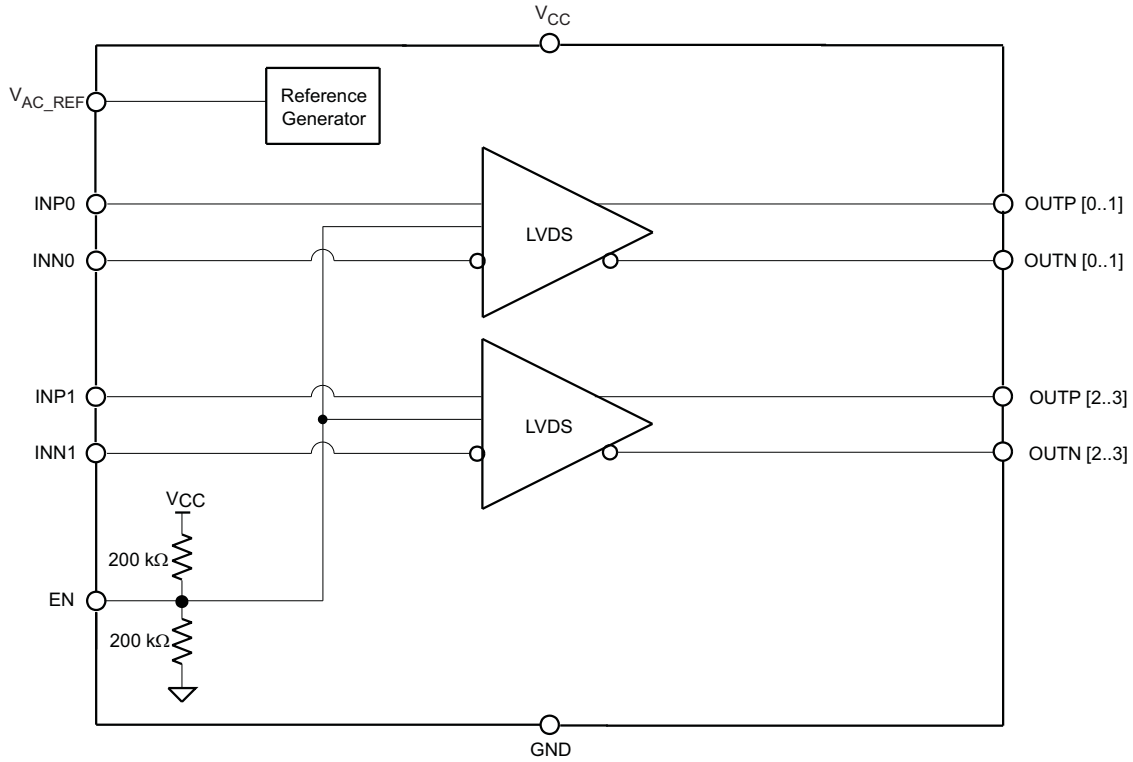
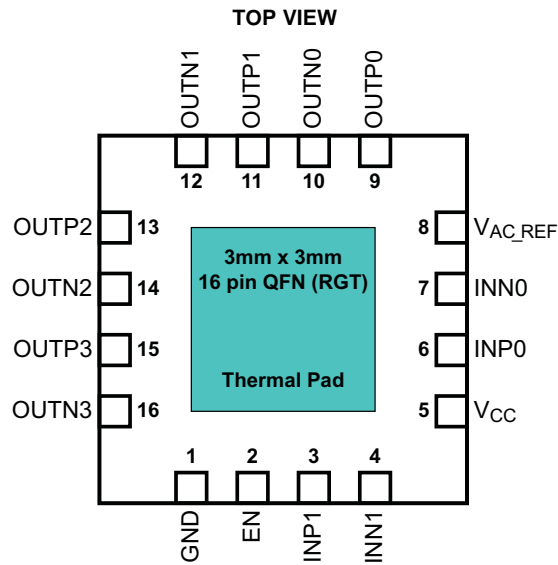


Figure 2. CDCLVD2102 Block Diagram



PIN FUNCTIONS

| PIN | | TYPE | DESCRIPTION | |
|---------------------|--------|---|---|------------------------|
| NAME | NO. | | | |
| VCC | 5 | Power | 2.5V supplies for the device | |
| GND | 1 | Ground | Device ground | |
| INP0, INN0 | 6, 7 | Input | Differential input pair or single ended input | |
| INP1, INN1 | 3, 4 | Input | Differential redundant input pair or single ended input | |
| V _{AC_REF} | 8 | Output | Bias voltage output for capacitive coupled inputs. If used, it is recommended to use a 0.1µF to GND on this pin | |
| OUTP0, OUTN0 | 9, 10 | Output | Differential LVDS output pair no. 0 | INP0/INN0 is the input |
| OUTP1, OUTN1 | 11, 12 | Output | Differential LVDS output pair no. 1 | |
| OUTP2, OUTN2 | 13, 14 | Output | Differential LVDS output pair no. 2 | INP1/INN1 is the input |
| OUTP3, OUTN3 | 15, 16 | Output | Differential LVDS output pair no. 3 | |
| EN | 2 | Input with internal 200kΩ pull-up and pull-down | Control pin – enables or disables the outputs, (See Table 1) | |
| Thermal Pad | | | See thermal management recommendations | |

Table 1. Output Control Table

| EN | CLOCK OUTPUTS |
|------|---|
| 0 | All outputs disabled (static "0") |
| OPEN | All outputs enabled |
| 1 | OUT0, OUT1 enabled and OUT2, OUT3 disabled (static "0") |

ABSOLUTE MAXIMUM RATINGS

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | VALUE / UNIT |
|--|-----------------------------------|
| Supply voltage range, V _{CC} | –0.3 to 2.8 V |
| Input voltage, V _I | –0.2 to (V _{CC} + 0.2) V |
| Output voltage range, V _O | –0.2 to (V _{CC} + 0.2) V |
| Driver short circuit current, I _{OSD} | See Note ⁽²⁾ |
| Electrostatic discharge (HBM, 1.5 kΩ, 100 pF) | >3000 V |

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions” is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.

(2) The outputs can handle permanent short.

RECOMMENDED OPERATING CONDITIONS

| | MIN | TYP | MAX | UNITS |
|--|-------|-----|-------|-------|
| Device supply voltage, V _{CC} | 2.375 | 2.5 | 2.625 | V |
| Ambient temperature, T _A | –40 | | 85 | °C |

THERMAL INFORMATION

| THERMAL METRIC ⁽¹⁾ | | CDCLVD2102 | UNITS |
|-------------------------------|--|------------|-------|
| | | RGT | |
| | | 16 PINS | |
| θ_{JA} | Junction-to-ambient thermal resistance | 51.3 | °C/W |
| $\theta_{JC(top)}$ | Junction-to-case(top) thermal resistance | 85.4 | |
| θ_{JB} | Junction-to-board thermal resistance | 20.1 | |
| ψ_{JT} | Junction-to-top characterization parameter | 1.3 | |
| ψ_{JB} | Junction-to-board characterization parameter | 19.4 | |
| $\theta_{JC(bottom)}$ | Junction-to-case(bottom) thermal resistance | 6 | |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

ELECTRICAL CHARACTERISTICS:

At $V_{CC} = 2.375\text{ V}$ to 2.625 V and $T_A = -40^\circ\text{C}$ to 85°C (unless otherwise noted).

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---|---|---------------------|---------------------|---------------|
| EN PIN INPUT CHARACTERISTICS | | | | | |
| V_{dI3} | 3-State | Open | $0.5 \times V_{CC}$ | | V |
| V_{dIH} | Input high voltage | | $0.7 \times V_{CC}$ | | V |
| V_{dIL} | Input low voltage | | | $0.2 \times V_{CC}$ | V |
| I_{dIH} | Input high current | $V_{CC} = 2.625\text{ V}$, $V_{IH} = 2.625\text{ V}$ | | 30 | μA |
| I_{dIL} | Input low current | $V_{CC} = 2.625\text{ V}$, $V_{IL} = 0\text{ V}$ | | -30 | μA |
| $R_{pull(EN)}$ | Input pull-up/ pull-down resistor | | 200 | | k Ω |
| 2.5V LVC MOS (see Figure 7) INPUT CHARACTERISTICS | | | | | |
| f_{IN} | Input frequency | | | 200 | MHz |
| V_{th} | Input threshold voltage | External threshold voltage applied to complementary input | 1.1 | 1.5 | V |
| V_{IH} | Input high voltage | | $V_{th} + 0.1$ | V_{CC} | V |
| V_{IL} | Input low voltage | | 0 | $V_{th} - 0.1$ | V |
| I_{IH} | Input high current | $V_{CC} = 2.625\text{ V}$, $V_{IH} = 2.625\text{ V}$ | | 10 | μA |
| I_{IL} | Input low current | $V_{CC} = 2.625\text{ V}$, $V_{IL} = 0\text{ V}$ | | -10 | μA |
| $\Delta V/\Delta T$ | Input edge rate | 20% – 80% | 1.5 | | V/ns |
| C_{IN} | Input capacitance | | 2.5 | | pF |
| DIFFERENTIAL INPUT CHARACTERISTICS | | | | | |
| f_{IN} | Input frequency | Clock input | | 800 | MHz |
| $V_{IN, DIFF}$ | Differential input voltage peak-to-peak | $V_{ICM} = 1.25\text{ V}$ | 0.3 | 1.6 | V_{P-P} |
| V_{ICM} | Input common-mode voltage range | $V_{IN, DIFF, PP} > 0.4\text{ V}$ | 1 | $V_{CC} - 0.3$ | V |
| I_{IH} | Input high current | $V_{CC} = 2.625\text{ V}$, $V_{IH} = 2.625\text{ V}$ | | 10 | μA |
| I_{IL} | Input low current | $V_{CC} = 2.625\text{ V}$, $V_{IL} = 0\text{ V}$ | | -10 | μA |
| $\Delta V/\Delta T$ | Input edge rate | 20% to 80% | 0.75 | | V/ns |
| C_{IN} | Input capacitance | | 2.5 | | pF |

ELECTRICAL CHARACTERISTICS: (continued)

 At $V_{CC} = 2.375\text{ V}$ to 2.625 V and $T_A = -40^\circ\text{C}$ to 85°C (unless otherwise noted).

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|--|--|-----|------|----------|------------------|
| LVDS OUTPUT CHARACTERISTICS | | | | | | |
| $ V_{OD} $ | Differential output voltage magnitude | $V_{IN, DIFF, PP} = 0.3\text{ V}, R_L = 100\ \Omega$ | 250 | | 450 | mV |
| ΔV_{OD} | Change in differential output voltage magnitude | | -15 | | 15 | mV |
| $V_{OC(SS)}$ | Steady-state common mode output voltage | | 1.1 | | 1.375 | V |
| $\Delta V_{OC(SS)}$ | Steady-state common mode output voltage | $V_{IN, DIFF, PP} = 0.6\text{ V}, R_L = 100\ \Omega$ | -15 | | 15 | mV |
| V_{ring} | Output overshoot and undershoot | Percentage of output amplitude V_{OD} | | | 10% | |
| V_{OS} | Output ac common mode | $V_{IN, DIFF, PP} = 0.6\text{ V}, R_L = 100\ \Omega$ | | 25 | 70 | mV _{PP} |
| I_{OS} | Short-circuit output current | $V_{OD} = 0\text{ V}$ | | | ± 24 | mA |
| t_{PD} | Propagation delay | $V_{IN, DIFF, PP} = 0.3\text{ V}$ | | 1.5 | 2.5 | ns |
| $t_{SK, PP}$ | Part-to-part skew | | | | 600 | ps |
| t_{SK, O_WB} | Within bank output skew | | | | 15 | ps |
| t_{SK, O_BB} | Bank-to-bank output skew | Both inputs are phase aligned | | | 100 | ps |
| $t_{SK, P}$ | Pulse skew(with 50% duty cycle input) | Crossing-point-to-crossing-point distortion | -50 | | 50 | ps |
| t_{RJIT} | Random additive jitter (with 50% duty cycle input) | Edge speed = 0.75 V/ns , 10 kHz – 20 MHz | | | 0.3 | ps, RMS |
| t_R/t_F | Output rise/fall time | 20% to 80%, $100\ \Omega$, 5 pF | 50 | | 300 | ps |
| I_{CCSTAT} | Static supply current | Outputs unterminated, $f = 0\text{ Hz}$ | | 27 | 45 | mA |
| I_{CC100} | Supply current | All outputs enabled, $R_L = 100\ \Omega$, $f = 100\text{ MHz}$ | | 49 | 77 | mA |
| I_{CC800} | Supply current | All outputs enabled, $R_L = 100\ \Omega$, $f = 800\text{ MHz}$ | | 76 | 106 | mA |
| V_{AC_REF} CHARACTERISTICS | | | | | | |
| V_{AC_REF} | Reference output voltage | $V_{CC} = 2.5\text{ V}, I_{load} = 100\ \mu\text{A}$ | 1.1 | 1.25 | 1.35 | V |

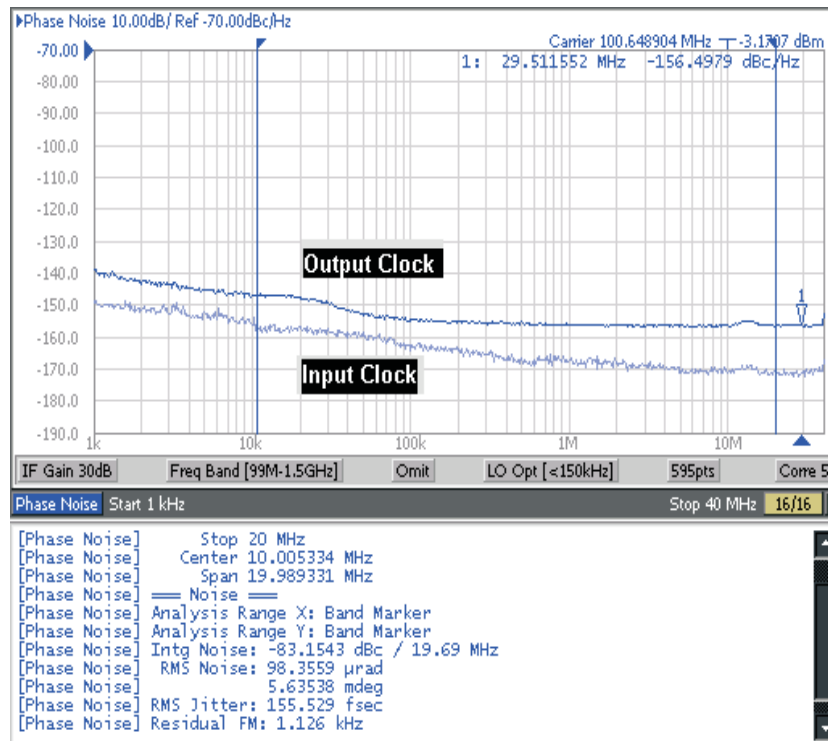
Typical Additive Phase Noise Characteristics for 100 MHz Clock

| PARAMETER | | MIN | TYP | MAX | UNIT |
|---------------------|--|-----|--------|-----|---------|
| phn ₁₀₀ | Phase noise at 100 Hz offset | | -132.9 | | dBc/Hz |
| phn _{1k} | Phase noise at 1 kHz offset | | -138.8 | | dBc/Hz |
| phn _{10k} | Phase noise at 10 kHz offset | | -147.4 | | dBc/Hz |
| phn _{100k} | Phase noise at 100 kHz offset | | -153.6 | | dBc/Hz |
| phn _{1M} | Phase noise at 1 MHz offset | | -155.2 | | dBc/Hz |
| phn _{10M} | Phase noise at 10 MHz offset | | -156.2 | | dBc/Hz |
| phn _{20M} | Phase noise at 20 MHz offset | | -156.6 | | dBc/Hz |
| t _{RJIT} | Random additive jitter from 10 kHz to 20 MHz | | 171 | | fs, RMS |

Typical Additive Phase Noise Characteristics for 737.27 MHz Clock

| PARAMETER | | MIN | TYP | MAX | UNIT |
|---------------------|--|-----|--------|-----|---------|
| phn ₁₀₀ | Phase noise at 100 Hz offset | | -80.2 | | dBc/Hz |
| phn _{1k} | Phase noise at 1 kHz offset | | -114.3 | | dBc/Hz |
| phn _{10k} | Phase noise at 10 kHz offset | | -138 | | dBc/Hz |
| phn _{100k} | Phase noise at 100 kHz offset | | -143.9 | | dBc/Hz |
| phn _{1M} | Phase noise at 1 MHz offset | | -145.2 | | dBc/Hz |
| phn _{10M} | Phase noise at 10 MHz offset | | -146.5 | | dBc/Hz |
| phn _{20M} | Phase noise at 20 MHz offset | | -146.6 | | dBc/Hz |
| t _{RJIT} | Random additive jitter from 10 kHz to 20 MHz | | 65 | | fs, RMS |

TYPICAL CHARACTERISTICS
INPUT CLOCK AND OUTPUT CLOCK PHASE NOISES
 vs
FREQUENCY FROM THE CARRIER ($T_A = 25^\circ\text{C}$ and $V_{CC} = 2.5\text{V}$)



Input clock jitter is 32 fs from 10 kHz to 20 MHz and additive RMS jitter is 152 fs

Figure 3. 100 MHz Input and Output Phase Noise Plot

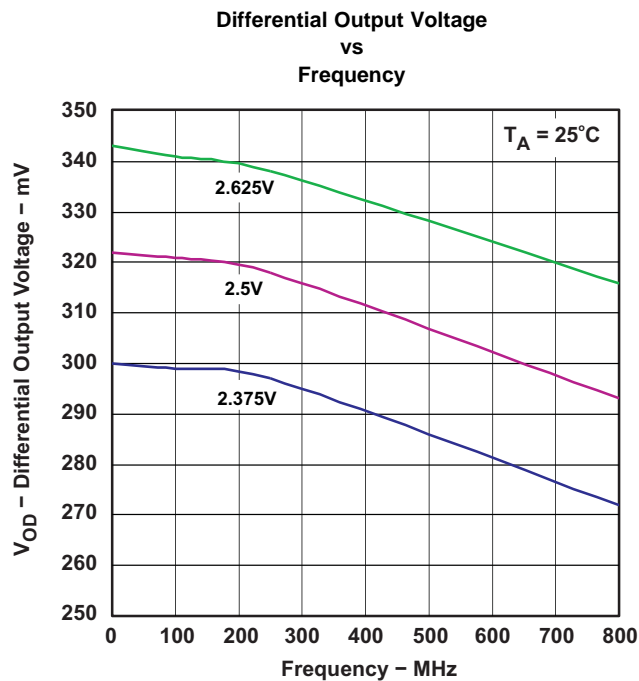


Figure 4.

TEST CONFIGURATIONS

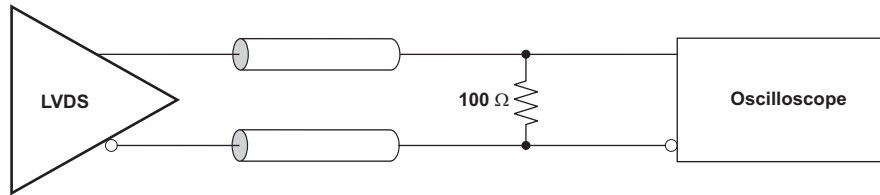


Figure 5. LVDS Output DC Configuration During Device Test

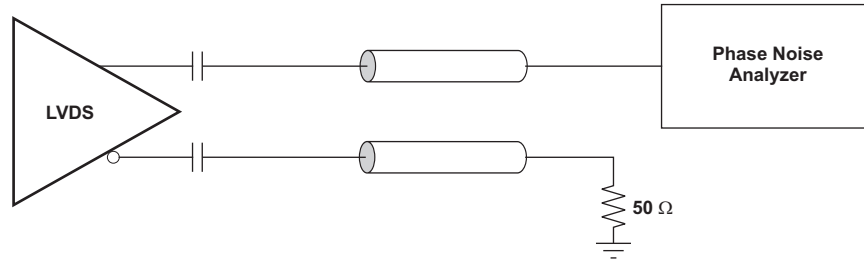


Figure 6. LVDS Output AC Configuration During Device Test

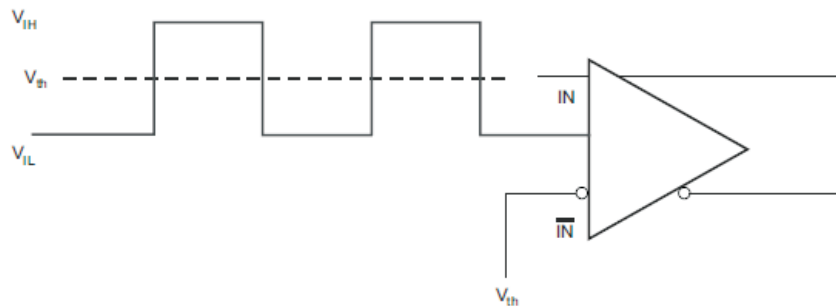


Figure 7. DC Coupled LVCMOS Input During Device Test

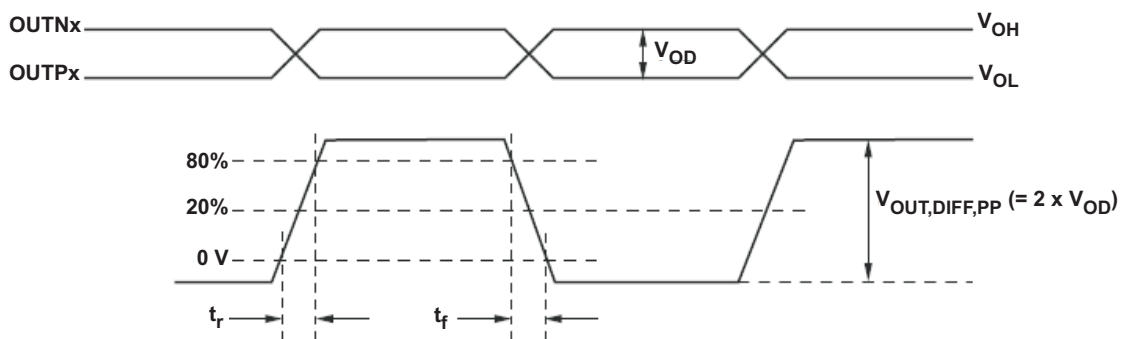
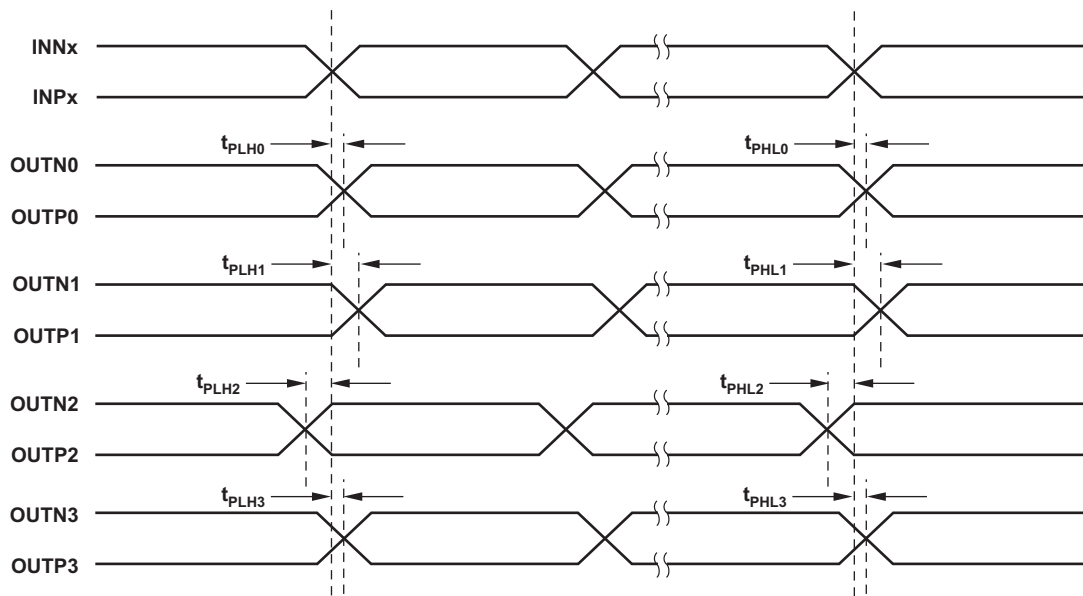


Figure 8. Output Voltage and Rise/Fall Time



- A. Output skew is calculated as the greater of the following: As the difference between the fastest and the slowest t_{PLHn} or the difference between the fastest and the slowest t_{PHLn} ($n = 0, 1, 2, 3$).
- B. Part-to-part skew is calculated as the greater of the following: As the difference between the fastest and the slowest t_{PLHn} or the difference between the fastest and the slowest t_{PHLn} across multiple devices ($n = 0, 1, 2, 3$).
- C. Both inputs ($IN0$ and $IN1$) are phase aligned.

Figure 9. Output Skew and Part-to-Part Skew

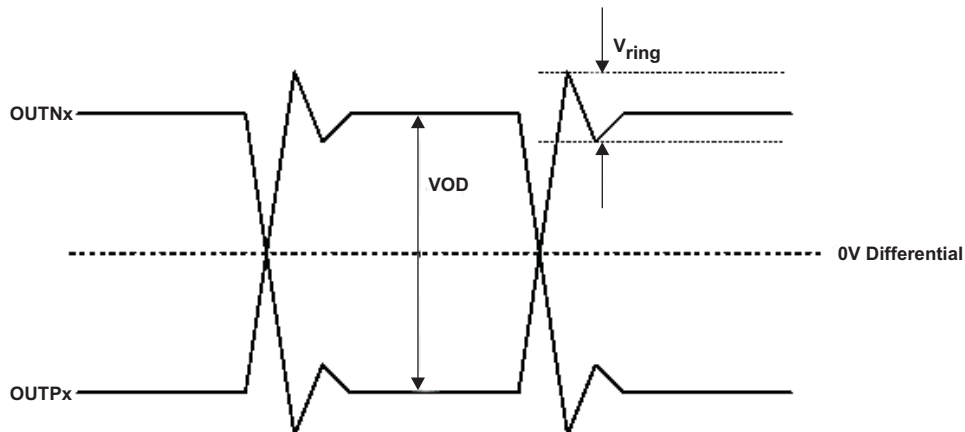


Figure 10. Output Overshoot and Undershoot

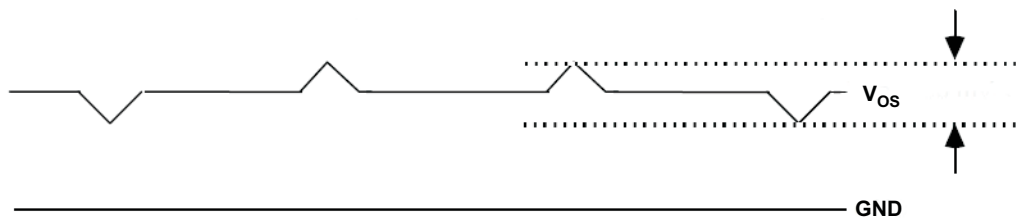


Figure 11. Output AC Common Mode

APPLICATION INFORMATION

THERMAL MANAGEMENT

For reliability and performance reasons, the die temperature should be limited to a maximum of 125°C.

The device package has an exposed pad that provides the primary heat removal path to the printed circuit board (PCB). To maximize the heat dissipation from the package, a thermal landing pattern including multiple vias to a ground plane must be incorporated into the PCB within the footprint of the package. The Thermal Pad must be soldered down to ensure adequate heat conduction to of the package. Figure 12 shows a recommended land and via pattern.

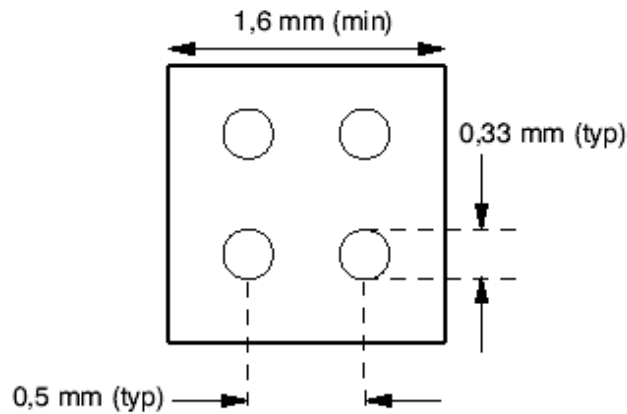


Figure 12. Recommended PCB Layout

POWER-SUPPLY FILTERING

High-performance clock buffers are sensitive to noise on the power supply, which can dramatically increase the additive jitter of the buffer. Thus, it is essential to reduce noise from the system power supply, especially when jitter/phase noise is critical to applications.

Filter capacitors are used to eliminate the low-frequency noise from the power supply, where the bypass capacitors provide the very low impedance path for high-frequency noise and guard the power-supply system against the induced fluctuations. These bypass capacitors also provide instantaneous current surges as required by the device and should have low equivalent series resistance (ESR). To properly use the bypass capacitors, they must be placed very close to the power-supply pins and laid out with short loops to minimize inductance. It is recommended to add as many high-frequency (for example, 0.1 μF) bypass capacitors as there are supply pins in the package. It is recommended, but not required, to insert a ferrite bead between the board power supply and the chip power supply that isolates the high-frequency switching noises generated by the clock driver; these beads prevent the switching noise from leaking into the board supply. Choose an appropriate ferrite bead with very low dc resistance because it is imperative to provide adequate isolation between the board supply and the chip supply, as well as to maintain a voltage at the supply pins that is greater than the minimum voltage required for proper operation.

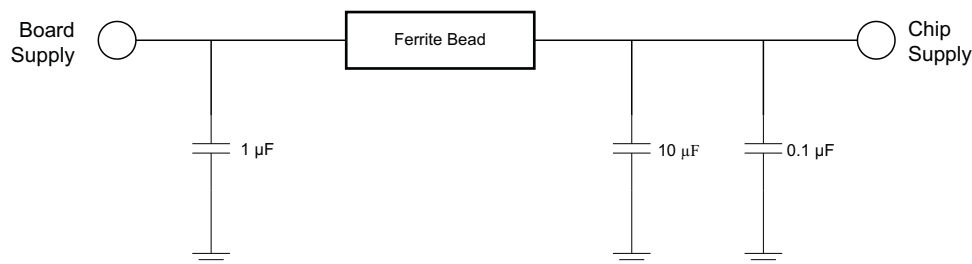


Figure 13. Power-Supply Decoupling

LVDS OUTPUT TERMINATION

The proper LVDS termination for signal integrity over two 50 Ω lines is 100 Ω between the outputs on the receiver end. Either dc-coupled termination or ac-coupled termination can be used for LVDS outputs. It is recommended to place termination resistor close to the receiver. If the receiver is internally biased to a voltage different than the output common mode voltage of the CDCLVD2102, ac-coupling should be used. If the LVDS receiver has internal 100 ohm termination, external termination must be omitted.

Unused outputs can be left open without connecting any trace to the output pins.

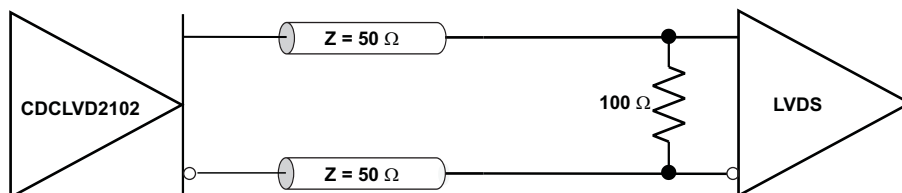


Figure 14. Output DC Termination

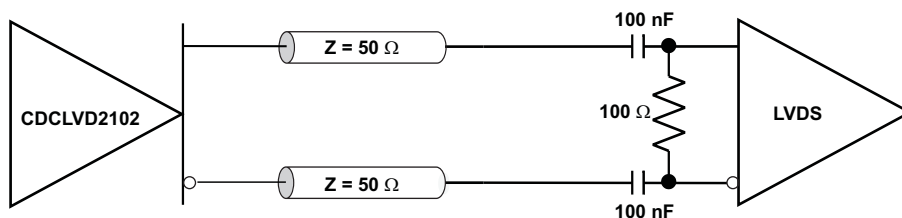


Figure 15. Output AC Termination With Receiver Internally Biased

INPUT TERMINATION

The CDCLVD2102 inputs can be interfaced with LVDS, LVPECL, or LVCMOS drivers.

LVDS Driver can be connected to CDCLVD2102 inputs with dc or ac coupling as shown [Figure 16](#) and [Figure 17](#), respectively.

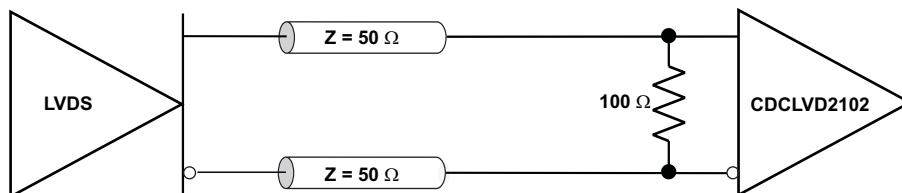


Figure 16. LVDS Clock Driver Connected to CDCLVD2102 Input (DC Coupled)

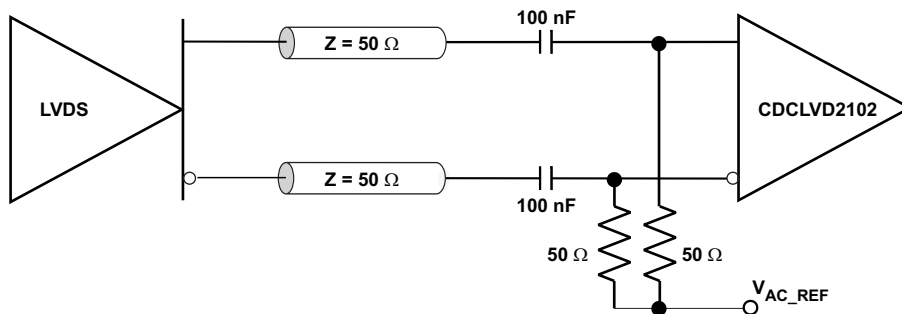


Figure 17. LVDS Clock Driver Connected to CDCLVD2102 Input (AC Coupled)

Figure 18 shows how to connect LVPECL inputs to the CDCLVD2102. The series resistors are required to reduce the LVPECL signal swing if the signal swing is $>1.6 V_{PP}$.

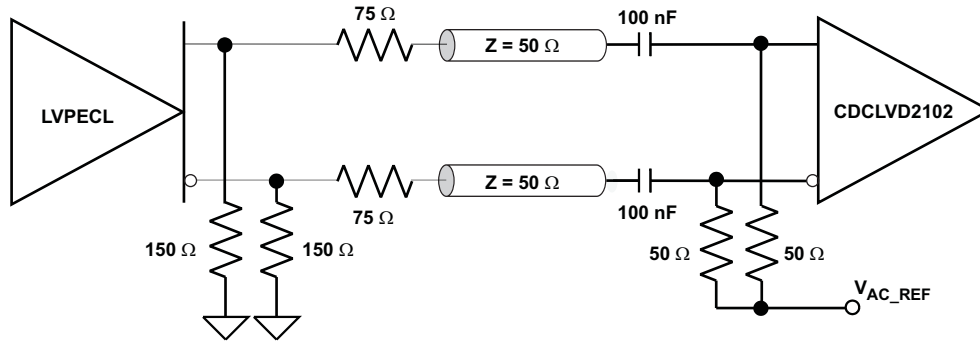


Figure 18. LVPECL Clock Driver Connected to CDCLVD2102 Input

Figure 19 illustrates how to couple a 2.5 V LVCMOS clock input to the CDCLVD2102 directly. The series resistance (R_S) should be placed close to the LVCMOS driver if needed. 3.3 V LVCMOS clock input swing needs to be limited to $V_{IH} \leq V_{CC}$.

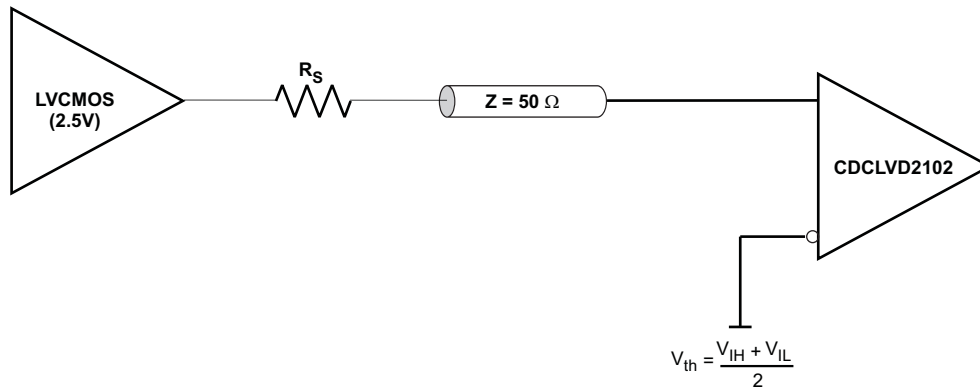


Figure 19. 2.5V LVCMOS Clock Driver Connected to CDCLVD2102 Input

If one of the buffers is used, then the other unused buffer should be disabled through the EN pin, and the unused input pins should be grounded by 1kΩ resistors.

REVISION HISTORY

| Changes from Original (May 2010) to Revision A | Page |
|--|------|
| • Changed Features bullet From: ESD Protection Exceeds 2kV HBM, 500V CDM To: ESD Protection Exceeds 3 kV HBM, 1 kV CDM | 1 |
| • Electrostatic discharge was <2000 | 3 |
| • ΔV_{OD} values, MIN was -50, MAX was 50 | 5 |
| • $V_{OC(SS)}$ MIN value was 1.125 | 5 |
| • $\Delta V_{OC(SS)}$ values, MIN was -50, MAX was 50 | 5 |
| • V_{ring} MAX value was 20% | 5 |
| • V_{OS} values, TYP was 30, MAX was 100 | 5 |
| • t_{PD} MAX value was 2 | 5 |
| • $t_{SK, PP}$ - deleted the TYP value of 300 | 5 |
| • t_R/t_F MIN value was 200 | 5 |
| • I_{CCSTAT} MAX value was 42 | 5 |
| • Added new paragraph following Figure 19 | 12 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|----------------|
| CDCLVD2102RGTR | ACTIVE | VQFN | RGT | 16 | 3000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | D2102 | Samples |
| CDCLVD2102RGTT | ACTIVE | VQFN | RGT | 16 | 250 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | D2102 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CDCLVD2102RGTR | VQFN | RGT | 16 | 3000 | 330.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

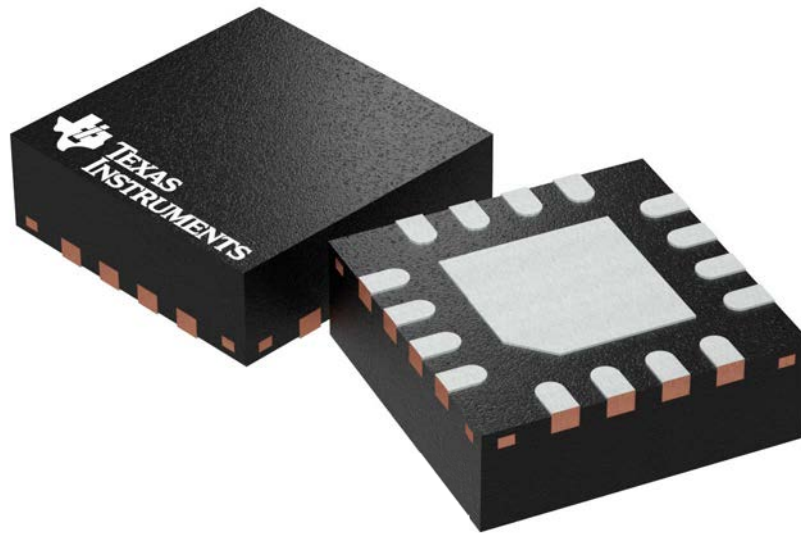
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CDCLVD2102RGTR | VQFN | RGT | 16 | 3000 | 350.0 | 350.0 | 43.0 |

RGT 16

GENERIC PACKAGE VIEW

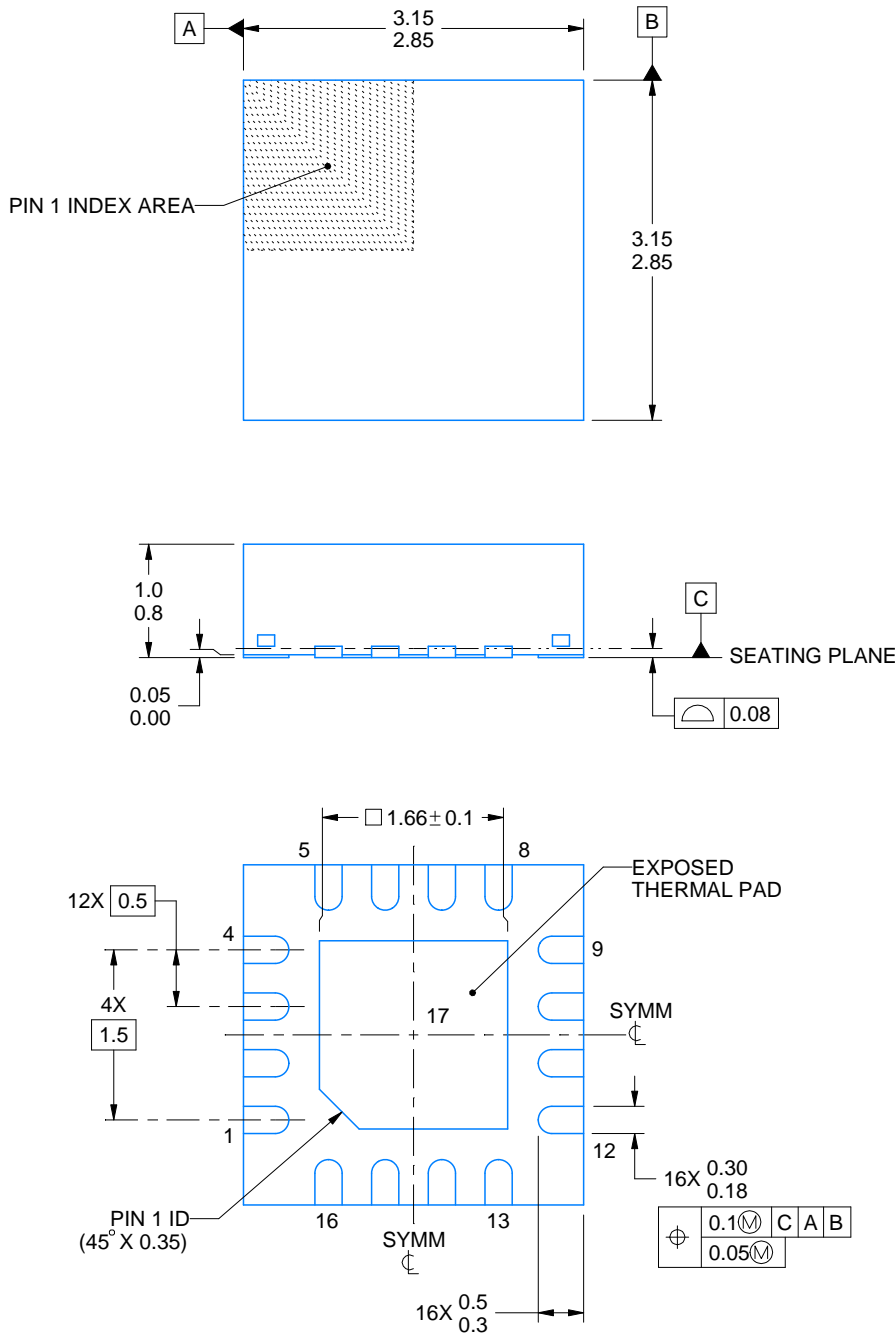
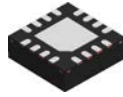
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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NOTES:

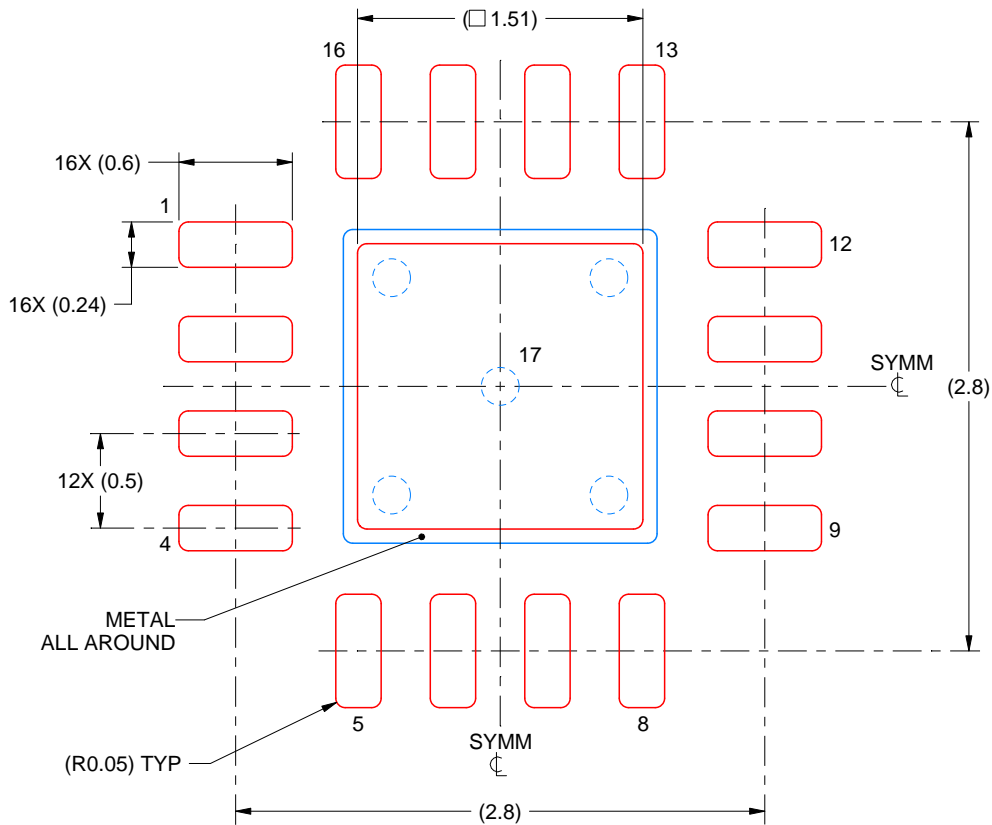
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE STENCIL DESIGN

RGT0016P

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17:
84% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:25X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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